

DIA-X BOND™

Universal

*X-traordinary Strength,
Remarkably Simple.*

INDICATIONS FOR USE:

- 🦷 All direct restorations:
Resin-based composite, resin-modified glass ionomers,
core build-up, resin cement, etc.
- 🦷 All indirect restorations:
metal, zirconia, glass ceramics, alumina, etc.
- 🦷 Desensitization/Sealing of Tooth
- 🦷 Intraoral Repair
(chipped porcelain, additions to direct restorations, etc.)



DIA-X BOND™

Universal

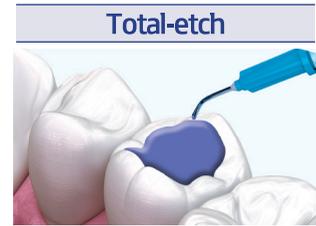
VERSATILITY:
All Etching Techniques



No phosphoric acid



Phosphoric acid on enamel



Phosphoric acid on enamel and dentin

Step-by-Step Instructions

• Direct Restoration



• Indirect Restoration

Select the etching technique:

Self-etch >> Start from Step 02 if etchant is not used



Selective-etch



Total-etch



Apply bond & rub for 20 seconds



Air dry for 5 seconds (do not desiccate)



Light cure for at least 10 seconds



Apply bond on inlays/onlays



Cementation



Final restoration

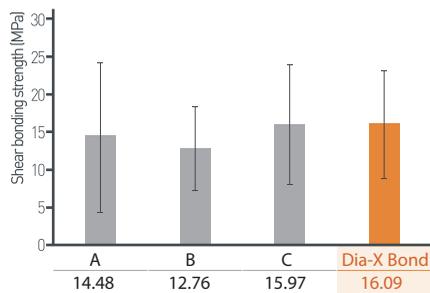
• Desensitization/Sealing of Tooth



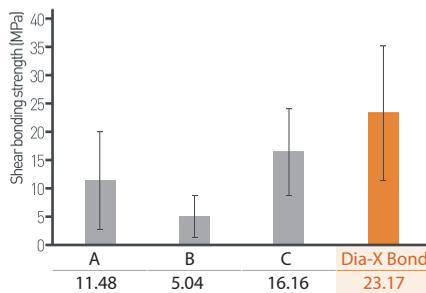
• Intra-Oral Repair



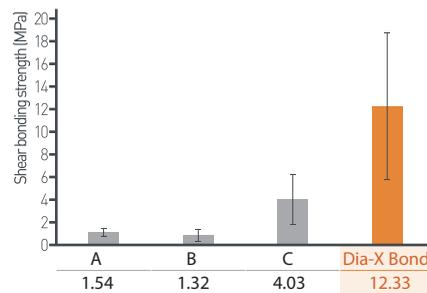
Indirect Restoration Material Comparison Tests



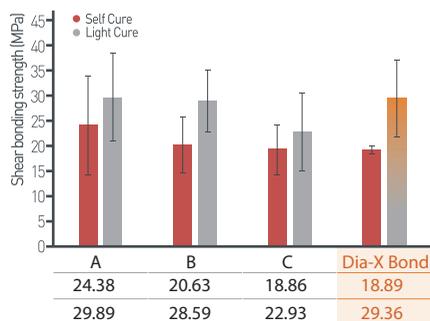
<Zirconia>



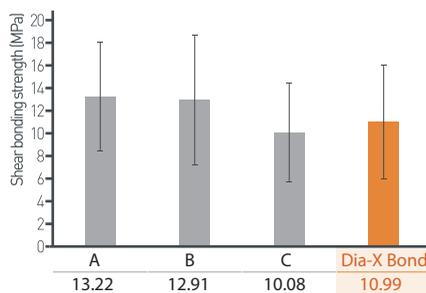
<Metal>



<Ceramic (Porcelain)>



<Light Cure Resin Cement>

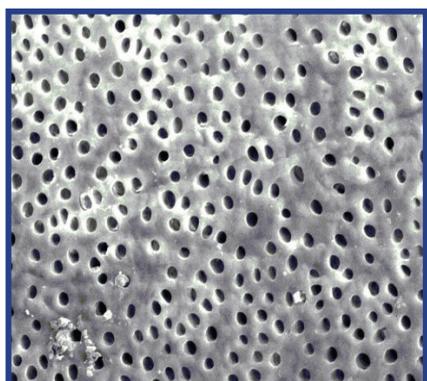


<RMGI>

Conditions:

- Number of specimens: 5 ea
- Light curing with D-Lux+ (high mode 10 secs)
- Resin cement: Self-cure at 6.5 minutes at 37°C
- 24H / 37°C / 0.75 mm/min shear adhesive strength measurement

Desensitization / Dentin Tubules Occlusion



SEM HV - 20.00kV
View Field - 144.5 µm
SEM MAG - 2.00 kx
WD - 20.07mm
Det - SE
Date(m/d/y) - 11/27/20



SEM HV - 20.00kV
View Field - 144.5 µm
SEM MAG - 2.00 kx
WD - 22.40mm
Det - SE
Date(m/d/y) - 11/27/20

SEM shows Dia-X Bond Universal's desensitization effectiveness by completely occluding the dentin tubules.